

500V N-Channel MOSFET

General Features

- Proprietary New Planar Technology
- $R_{DS(ON),typ.}=0.24\ \Omega @ V_{GS}=10V$
- Low Gate Charge Minimize Switching Loss
- Fast Recovery Body Diode

Applications

- Adaptor Charger
- SMPS Power Supply
- LCD Panel Power

Ordering Information

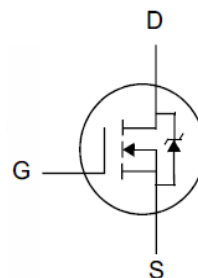
PART NUMBE	SK20N50A-T7
PACKAGE	TO-247

BV_{DSS}	$R_{DS(ON),typ.}$	I_D
500V	0.24 Ω	20A



TO-247

Package



Absolute Maximum Ratings

$T_C=25^{\circ}C$ unless otherwise specified

Symbol	Parameter	SK20N50A-T7	Unit
V_{DSS}	Drain-to-Source Voltage ^[1]	500	V
V_{GSS}	Gate-to-Source Voltage	± 30	
I_D	Continuous Drain Current	20	A
$I_D @ T_C=100^{\circ}C$	Continuous Drain Current @ $T_C=100^{\circ}C$	Figure 3	
I_{DM}	Pulsed Drain Current at $V_{GS}=10V$ ^[2]	Figure 6	
E_{AS}	Single Pulse Avalanche Energy	1800	mJ
dv/dt	Peak Diode Recovery dv/dt ^[3]	5.0	V/ns
P_D	Power Dissipation	275	W
	Derating Factor above $25^{\circ}C$	2.2	W/ $^{\circ}C$
T_L T_{PAK}	Maximum Temperature for Soldering Leads at 0.063in (1.6mm) from Case for 10 seconds, Package Body for 10 seconds	300 260	$^{\circ}C$
$T_J \& T_{STG}$	Operating and Storage Temperature Range	-55 to 150	

Caution: Stresses greater than those listed in the "Absolute Maximum Ratings" may cause permanent damage to the device.

Thermal Characteristics

Symbol	Parameter	SK20N50A-T7	Unit
$R_{\theta JC}$	Thermal Resistance, Junction-to-Case	0.45	$^{\circ}C/W$
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient	60	

Electrical Characteristics

OFF Characteristics $T_J = 25^\circ\text{C}$ unless otherwise specified

Symbol	Parameter	Min.	Typ.	Max.	Unit	Test Conditions
BV_{DSS}	Drain-to-Source Breakdown Voltage	500	--	--	V	$V_{GS}=0V, I_D=250\mu A$
I_{DSS}	Drain-to-Source Leakage Current	--	--	1	μA	$V_{DS}=500V, V_{GS}=0V$
		--	--	100		$V_{DS}=400V, V_{GS}=0V, T_J=125^\circ\text{C}$
I_{GSS}	Gate-to-Source Leakage Current	--	--	+100	nA	$V_{GS}=+30V, V_{DS}=0V$
		--	--	-100		$V_{GS}=-30V, V_{DS}=0V$

ON Characteristics

$T_J = 25^\circ\text{C}$ unless otherwise specified

Symbol	Parameter	Min.	Typ.	Max.	Unit	Test Conditions
$R_{DS(ON)}$	Static Drain-to-Source On-Resistance ^[4]	--	0.24	0.30	Ω	$V_{GS}=10V, I_D=10A$
$V_{GS(TH)}$	Gate Threshold Voltage	2.0	--	4.0	V	$V_{DS}=V_{GS}, I_D=250\mu A$
gfs	Forward Transconductance ^[4]	--	18	--	S	$V_{DS}=15V, I_D=10A$

Dynamic Characteristics

Essentially independent of operating temperature

Symbol	Parameter	Min.	Typ.	Max.	Unit	Test Conditions
C_{iss}	Input Capacitance	--	2670	--	pF	$V_{GS}=0V, V_{DS}=25V, f=1.0MHz$
C_{rss}	Reverse Transfer Capacitance	--	35	--		
C_{oss}	Output Capacitance	--	260	--		
Q_g	Total Gate Charge	--	65	--	nC	$V_{DD}=250V, I_D=20A, V_{GS}=0 \text{ to } 10V$
Q_{gs}	Gate-to-Source Charge	--	14	--		
Q_{gd}	Gate-to-Drain (Miller) Charge	--	24	--		

Resistive Switching Characteristics

Essentially independent of operating temperature

Symbol	Parameter	Min.	Typ.	Max.	Unit	Test Conditions
$t_{d(ON)}$	Turn-on Delay Time	--	35	--	nS	$V_{DD}=250V, I_D=20A, V_{GS}=10V, R_G=25\Omega$
t_{rise}	Rise Time	--	75	--		
$t_{d(OFF)}$	Turn-Off Delay Time	--	165	--		
t_{fall}	Fall Time	--	85	--		

Source-Drain Body Diode Characteristics

$T_J=25^{\circ}\text{C}$ unless otherwise specified

Symbol	Parameter	Min	Typ.	Max.	Unit	Test Conditions
I_{SD}	Continuous Source Current ^[4]	--	--	20	A	Integral PN-diode in MOSFET
I_{SM}	Pulsed Source Current ^[4]	--	--	80		
V_{SD}	Diode Forward Voltage	--	--	1.5	V	$I_S=20\text{A}$, $V_{GS}=0\text{V}$
t_{rr}	Reverse recovery time	--	320	--	ns	$V_{GS}=0\text{V}$, $I_F=20\text{A}$, $di_F/dt=100\text{A}/\mu\text{s}$
Q_{rr}	Reverse recovery charge	--	3.0	--	uC	

Note:

[1] $T_J=+25^{\circ}\text{C}$ to $+150^{\circ}\text{C}$

[2] Repetitive rating; pulse width limited by maximum junction temperature.

[3] $I_{SD}=20\text{A}$ $di/dt < 100\text{A}/\mu\text{s}$, $V_{DD} < B_{VDS}$, $T_J=+150^{\circ}\text{C}$.

[4] Pulse width $\leq 380\mu\text{s}$; duty cycle $\leq 2\%$.

Typical Characteristics

Figure 1. Maximum Transient Thermal Impedance

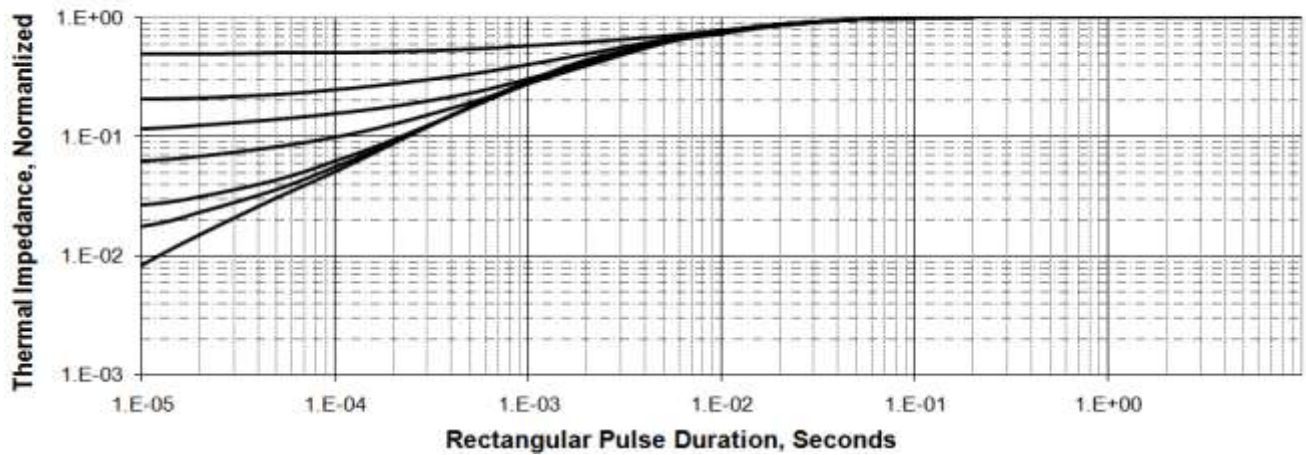


Figure 2 . Max. Power Dissipation vs Case Temperature

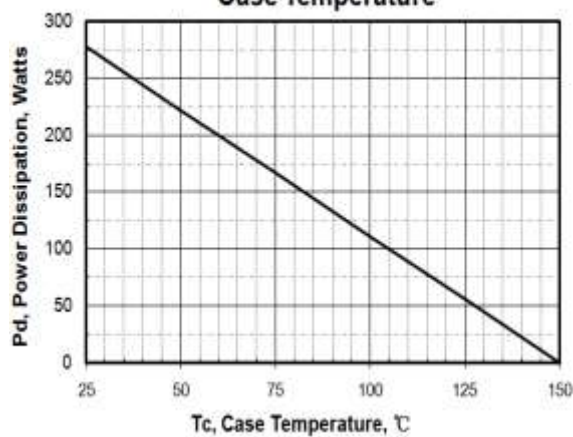


Figure 3 .Maximum Continuous Drain Current vs Tc

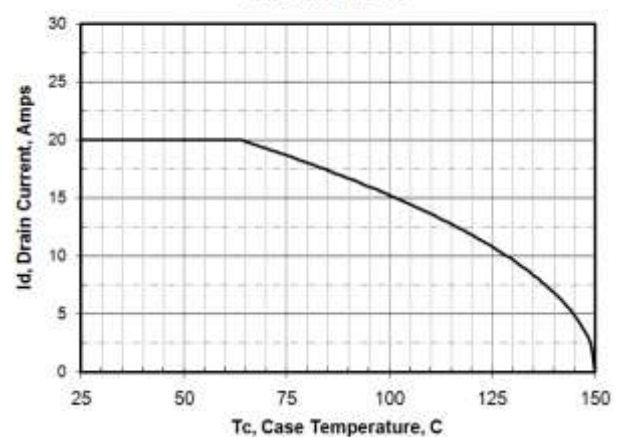


Figure 4. Typical Output Characteristics

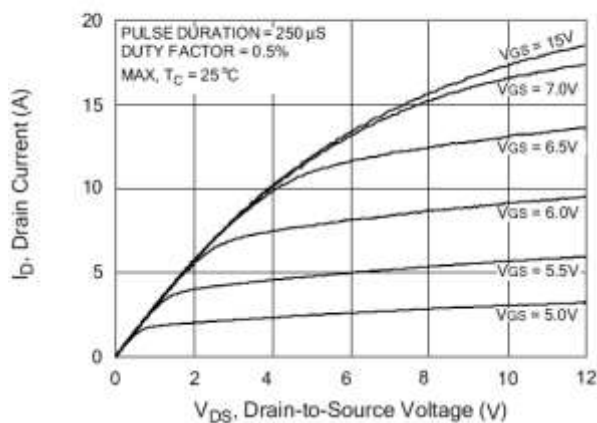
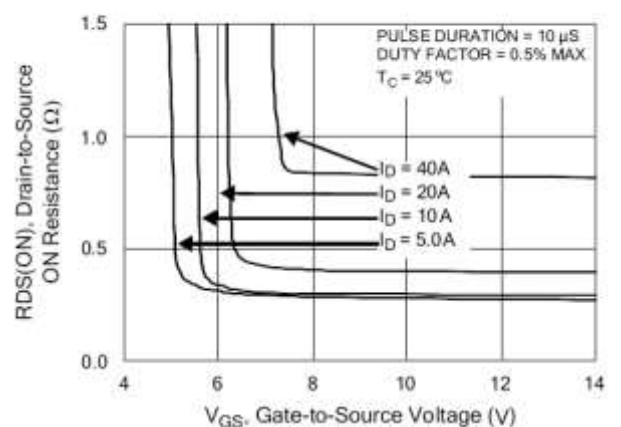


Figure 5. Typical Drain-to-Source ON Resistance vs Gate Voltage and Drain Current



Typical Characteristics

Figure 6. Maximum Peak Current Capability

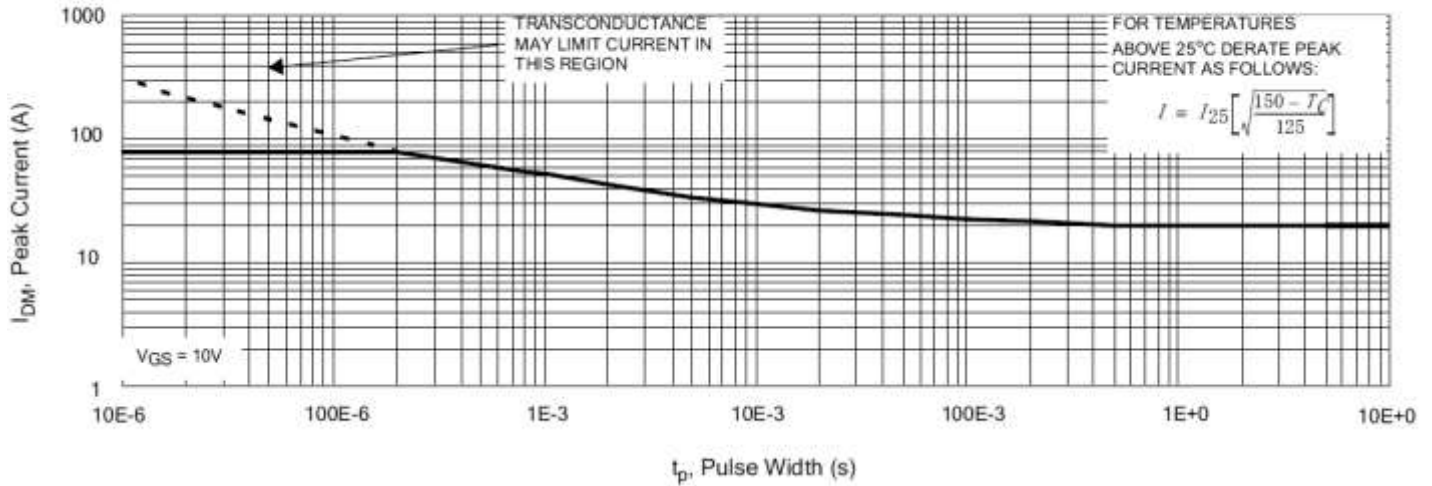


Figure 7. Typical Transfer Characteristics

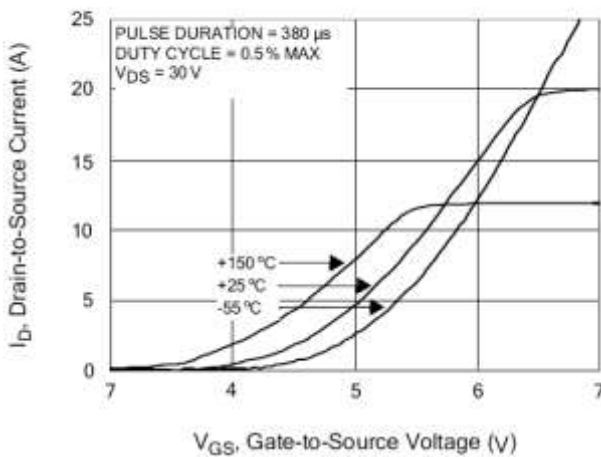


Figure 8. Unclamped Inductive Switching Capability

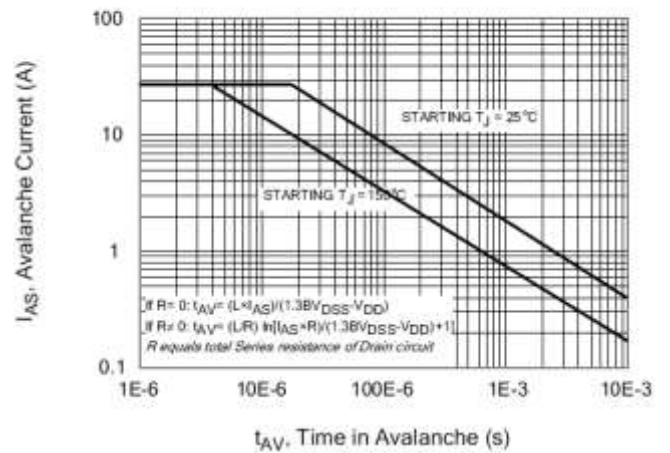


Figure 9. Typical Drain-to-Source ON Resistance vs Drain Current

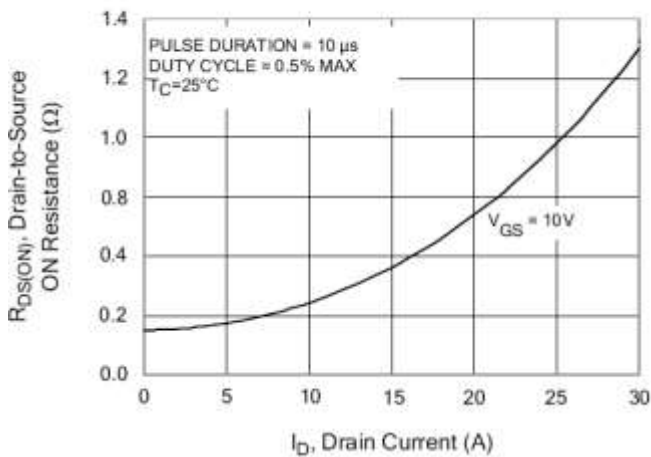
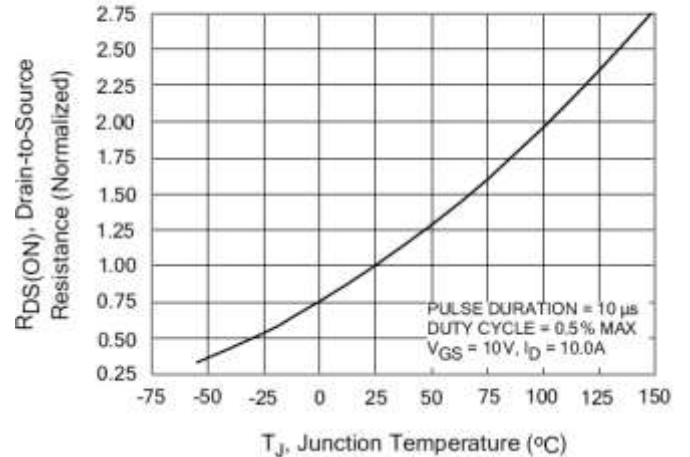


Figure 10. Typical Drain-to-Source ON Resistance vs Junction Temperature



Typical Characteristics

Figure 11. Typical Breakdown Voltage vs Junction Temperature

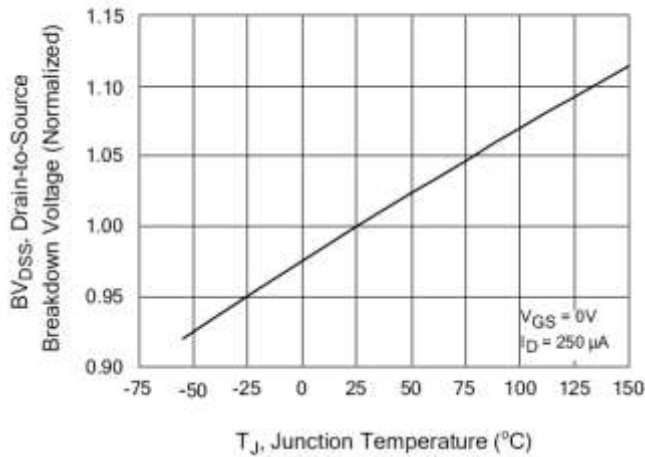


Figure 12. Typical Threshold Voltage vs Junction Temperature

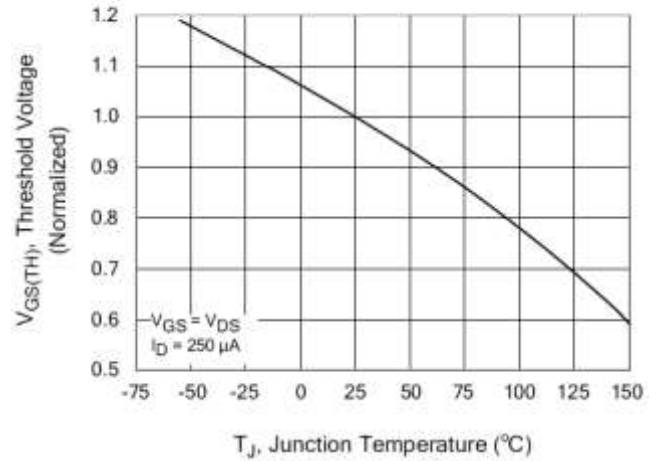


Figure 13. Maximum Forward Bias Safe Operating Area

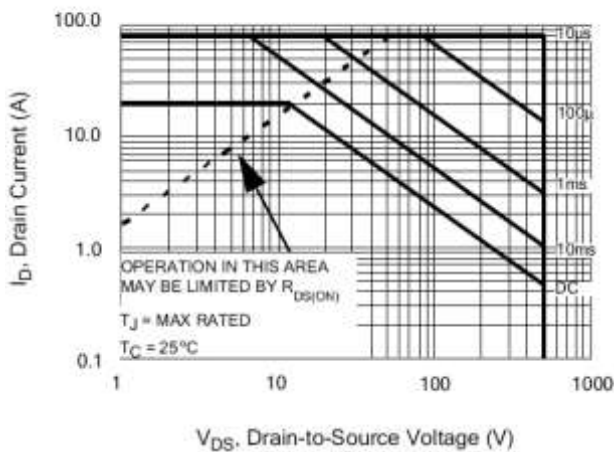


Figure 14. Typical Capacitance vs Drain-to-Source Voltage

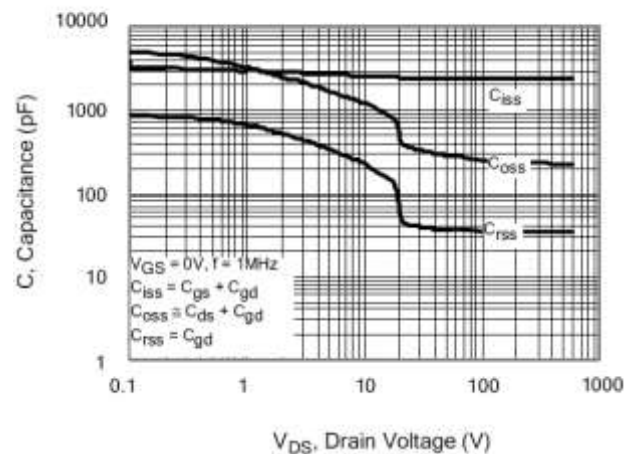


Figure 15. Typical Gate Charge vs Gate-to-Source Voltage

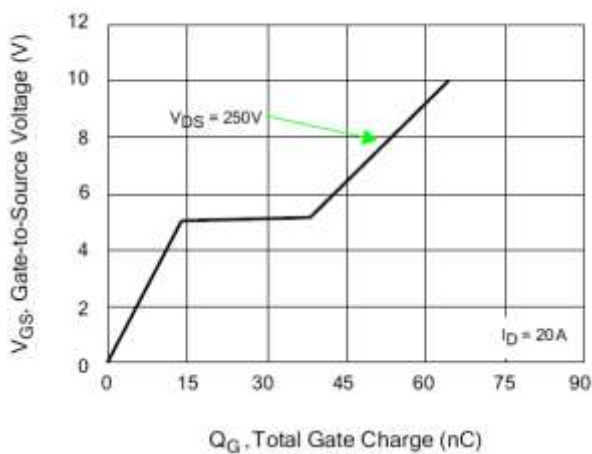
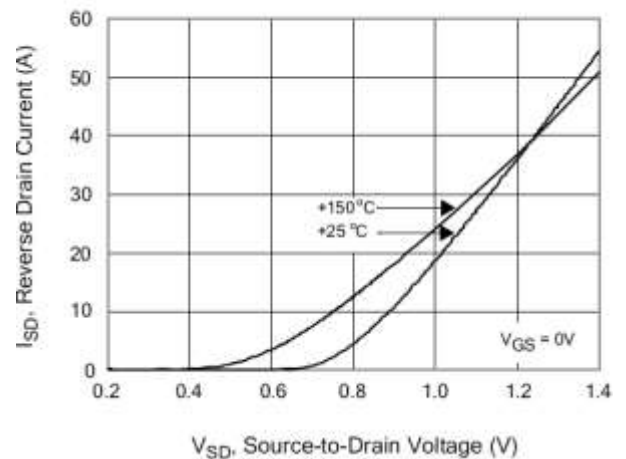
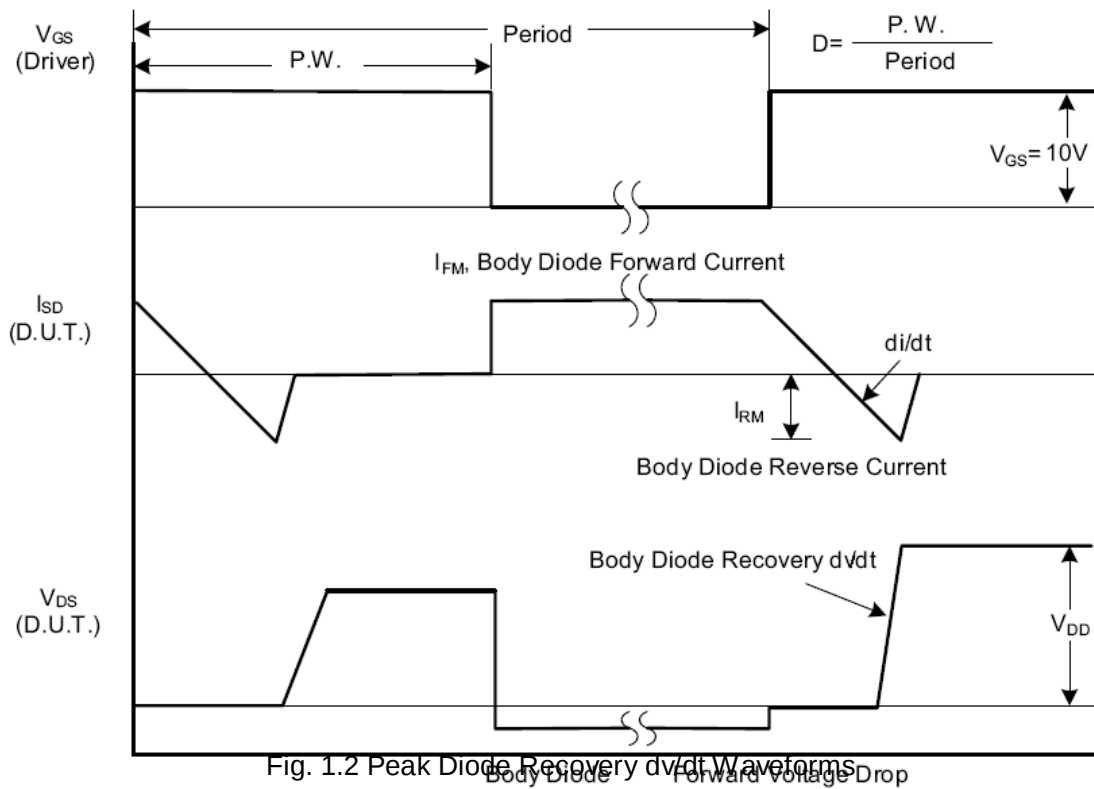
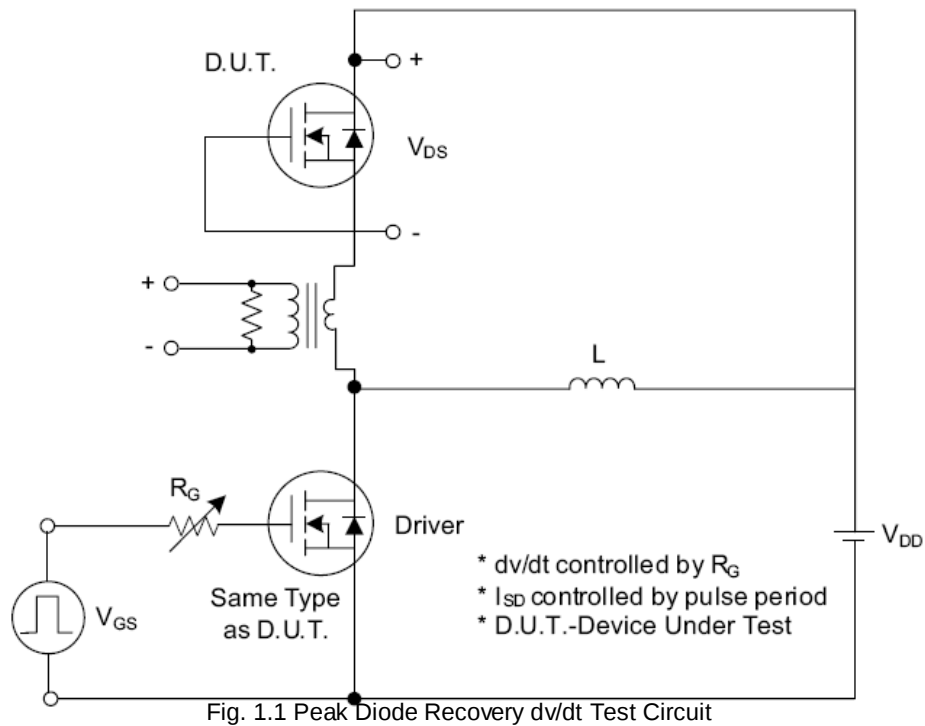


Figure 16. Typical Body Diode Transfer Characteristics



Test Circuits and Waveforms



Test Circuits and Waveforms (Cont.)

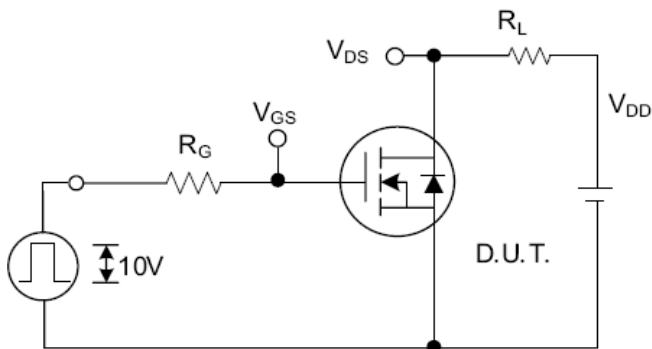


Fig. 2.1 Switching Test Circuit

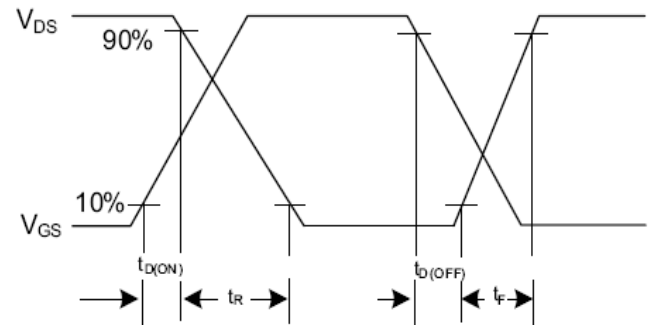


Fig. 2.2 Switching Waveforms

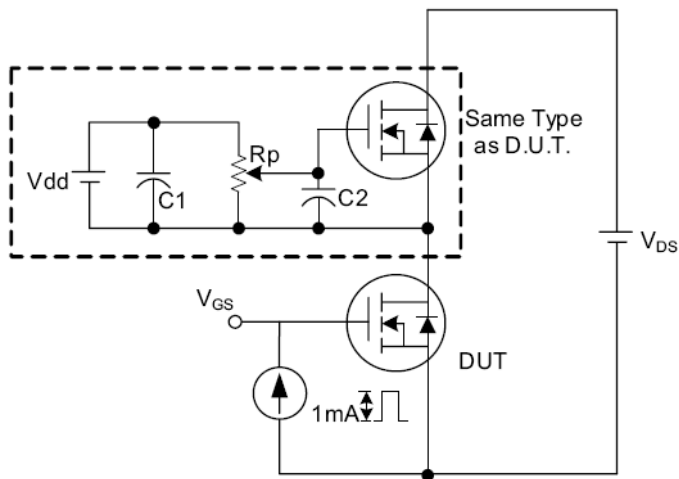


Fig. 3.1 Gate Charge Test Circuit

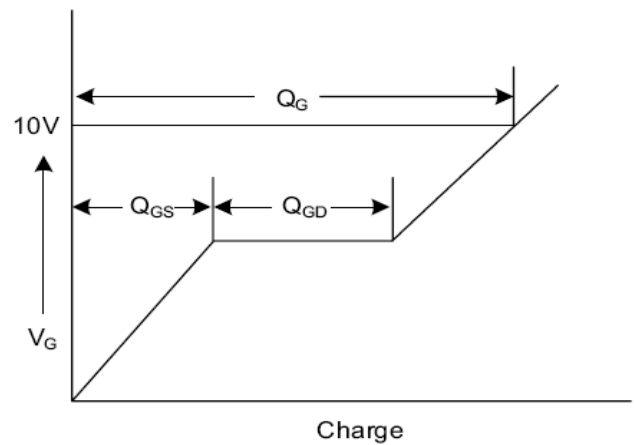


Fig. 3.2 Gate Charge Waveform

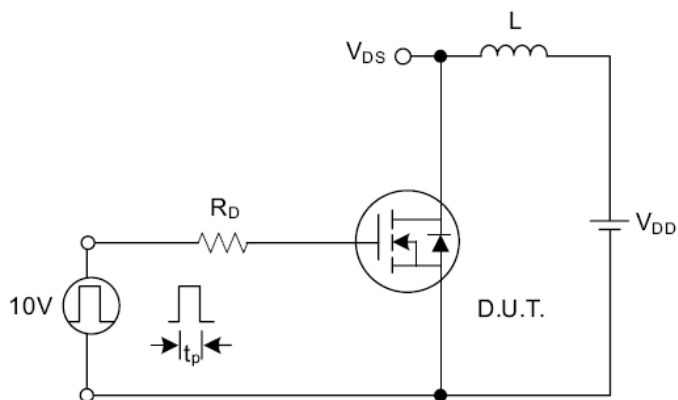


Fig. 4.1 Unclamped Inductive Switching Test Circuit

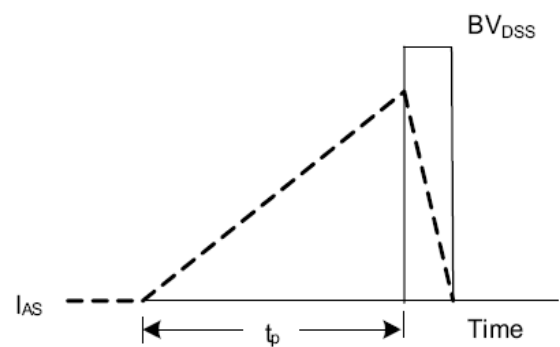
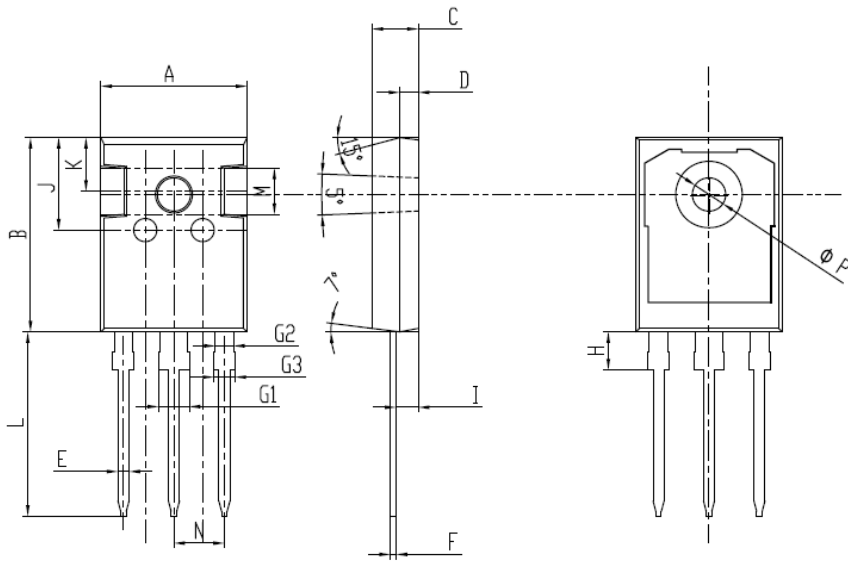


Fig. 4.2 Unclamped Inductive Switching Waveforms

PACKAGE OUTLINE

TO-247



	(mm)	
	MIN	MAX
A	15.70	15.90
B	20.90	21.10
C	4.90	5.10
D	1.90	2.10
E	1.10	1.30
F	0.45	0.75
G1	3.00	3.20
G2	1.85	2.15
G3	2.00	2.20
H	4.00	4.30
I	2.30	2.50
J	9.90	10.10
K	5.70	5.90
L	19.80	20.20
M	4.85	5.15
N	5.286	5.586
Φ P	3.40	3.60